Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L12	23442	ball adj grid adj array bga fgba efbga	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:47
L13	2	"6664617".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:47
L14	1	12 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:47
L15	2	"5760465".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:49
L16	2	13 or 14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:49
L17	3243857	computer camcorder video recorder coreder cameral cell phone	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:51
L18	0	16 and 17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:50
L19	1478937	chip die dice ic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:51
L20	98976	stiffen$4 stiffin$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:51
L21	13211	computer and (camcorder video recorder corder) and camera and phone	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:51

L22	20527	mcm (multi adj chip multichip multi-chip) adj module multi-chip-module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:52
L23	5	19 and 20 and 21 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:53
L24	92	21 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:58
L25	76	24 and (@ad < "20030919")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:53
L26	2	21 and "6229227".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:58
L27	2714	((257/684) or (257/690) or (257/793)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/19 18:07
S96	8	(("6611052") or ("6784525") or ("6791168") or ("6825569") or ("6835599") or ("6841883") or ("6853064") or ("6858467")).PN.	USPAT	OR	OFF	2005/05/18 13:21
S97	213	brewster-william-m.xa.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:31
S98	1844805	chip die dice ic package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:32
S99	2024831	epoxy resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:32

S10 0	1477538	chip die dice ic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:51
S10 1	27	S100 and S99 and S97	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:37
S10 2	23651	stiffener stiffiner	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:41
S10 3	1749033	chip die dice ic integrated adj circuit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:37
S10 4	98902	stiffen$4 stiffin$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:51
S10 5	12437	S100 and S104	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:41
S10 6	47671	ball adj grid adj array bga fgba efbga solder near2 (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:12
S10 7	3560	S100 and S102	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:41
S10 8	23655	stiffener stiffiner stifener stifiner	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:41
S10 9	3560	S100 and S108	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:42

S11 0	1542653	lead wire adj bond$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:42
S11 1	5917801	pad terminal contact electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:43
S11 2	1543	S109 and S110 and S111	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:45
S11 3	575681	mask$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:45
S11 4	409	S112 and S113	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 14:45
S11 5	358	S114 and (@ad < "20030919")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 15:14
S11 6	7763386	metal$4 copper steel copper cu fe nickel ni titanium ti aluminum al	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 15:12
S11 7	2764	S108 near4 S116	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 15:12
S11 8	1477538	chip die dice ic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 15:13
S11 9	149	S110 and S111 and S113 and S118 and S117	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 15:13

S12 0	116	S119 and (@ad < "20030919")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:39
S12 2	23655	stiffener stiffiner stifener stifiner	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:39
S12 3	1542653	lead wire adj bond$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:39
S12 4	5917801	pad terminal contact electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:39
S12 5	575681	mask$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:39
S12 6	7763386	metal$4 copper steel copper cu fe nickel ni titanium ti aluminum al	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:39
S12 7	2764	S122 near4 S126	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:39
S12 8	1477538	chip die dice ic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:14
S12 9	149	S123 and S124 and S125 and S128 and S127	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 16:39
S13 0	116	S129 and (@ad < "20030919")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:15

S13 1	2	"5760464".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 17:44
S13 2	2	S131 and (chips! dies! ics! dice! mcm multi multiple many second! another additional$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 17:42
S13 3	2	S131 and (chips dies ics dice mcm multi multiple many second! another additional$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 17:44
S13 4	2	"5760465".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:49
S13 5	1	S134 and (chips dies ics dice mcm multi multiple many second! another additional$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:09
S13 6	1	S134 and (wire bond$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:10
S13 7	2	S134 and (wire lead)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:12
S13 8	23400	ball adj grid adj array bga fgba efbga	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:47
S13 9	0	S134 and S138	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:12
S14 0	56919	wire adj bond$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:13

S141	20493	mcm (multi adj chip multichip multi-chip) adj module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:13
S142	20493	mcm (multi adj chip multichip multi-chip) adj module multi-chip-module	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 17:51
S143	1157690	chip die dice	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:14
S144	104	S143 and S140 and S141 and S122 and S138	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:15
S145	90	S144 and (@ad < "20030919")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:38
S146	2	"5767575".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:37
S147	1	S146 and S142	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/18 18:37
S148	24	S144 and (@ad < "20030919")	US-PGPUB	OR	ON	2005/05/18 18:38